### SKM 300 MLI 066 T



## SEMITRANS® 5

### Trench IGBT Modules

### SKM 300 MLI 066 T

**Target Data** 

### **Features**

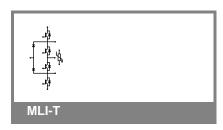
- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- Integrated NTC temperature sensor

### **Typical Applications**

- UPS
- 3 Level Inverter

### Remarks

 Case temperature limited to T<sub>c</sub> =125°C max, recommended T<sub>op</sub> = -40..+150°C



<b>Absolute Maximum Ratings</b> $T_{case} = 25^{\circ}C$ , unless otherwise specified						
Symbol	Conditions		Values	Units		
IGBT						
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		600	V		
I <sub>C</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	400	Α		
		T <sub>c</sub> = 80 °C	300	Α		
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		600	Α		
$V_{GES}$			± 20	V		
t <sub>psc</sub>	$V_{CC}$ = 360 V; $V_{GE} \le 15$ V; $V_{CES} < 600$ V	T <sub>j</sub> = 150 °C	6	μs		
Inverse Di	ode					
I <sub>F</sub>	T <sub>j</sub> = 150 °C	T <sub>c</sub> = 25 °C	324	Α		
		T <sub>c</sub> = 80 °C	211	Α		
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		420	Α		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; half sine wave	T <sub>j</sub> = 150 °C	2100	Α		
Freewhee	ling Diode					
I <sub>F</sub>	T <sub>j</sub> = 150 °C	$T_c = 25 ^{\circ}C$	324	Α		
		T <sub>c</sub> = 80 °C	211	Α		
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		420	Α		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; half sine wave	T <sub>j</sub> = 150 °C	2100	Α		
Module						
I <sub>t(RMS)</sub>			500	Α		
T <sub>vj</sub>			- 40 <b>+</b> 175	°C		
T <sub>stg</sub>			- 40 <b>+</b> 125	°C		
V <sub>isol</sub>	AC, 1 min.		2500	V		

Character	25°C, unless otherwise specified					
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 4.8 \text{ mA}$		5	5,8	6,5	V
I <sub>CES</sub>	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T <sub>j</sub> = 25 °C			0,015	mA
I <sub>GES</sub>	V <sub>CE</sub> = 0 V, V <sub>GE</sub> = 20 V	T <sub>j</sub> = 25 °C			1200	nA
$V_{CE0}$		T <sub>j</sub> = 25 °C		0,9	1	٧
		T <sub>j</sub> = 150 °C		0,85	0,9	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		1,8	3	mΩ
		T <sub>j</sub> = 150°C		2,7	3,8	$\text{m}\Omega$
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 300 A, V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C <sub>chiplev.</sub>		1,45	1,9	V
		T <sub>j</sub> = 150°C <sub>chiplev</sub> .		1,7	2,1	V
C <sub>ies</sub>				18,4		nF
C <sub>oes</sub>	$V_{CE}$ = 25, $V_{GE}$ = 0 V	f = 1 MHz		1,14		nF
C <sub>res</sub>				0,54		nF
R <sub>Gint</sub>	T <sub>j</sub> = °C			1		Ω
t <sub>d(on)</sub>						ns
t <sub>r</sub>	$R_{Gon} = 1 \Omega$	$V_{CC} = 300V$				ns
E <sub>on</sub>		I <sub>C</sub> = 300A		1,56		mJ
t <sub>d(off)</sub>	$R_{Goff} = 2 \Omega$	T <sub>j</sub> = 150 °C				ns
t <sub>f</sub>		$V_{GE} = -8V/+15V$				ns
E <sub>off</sub>				9,4		mJ
R <sub>th(j-c)</sub>	per IGBT			0,15		K/W

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- UPS
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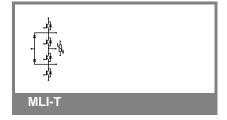
#### Remarks

 Case temperature limited to T<sub>c</sub> =125°C max, recommended T<sub>op</sub> = -40..+150°C

Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	Diode					•
$V_F = V_{EC}$	$I_{Fnom}$ = 245 A; $V_{GE}$ = 0 V	$T_j = 25  ^{\circ}C_{\text{chiplev.}}$		1,35	1,6	V
		$T_j = 125 ^{\circ}C_{chiplev.}$ $T_j = 25 ^{\circ}C$		1,35	1,6	V
$V_{F0}$				1	1,1	V
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$		0,9	1	V
r <sub>F</sub>				1,42	2	mΩ
		T <sub>j</sub> = 125 °C T <sub>j</sub> = 125 °C		1,8	2,4	mΩ
I <sub>RRM</sub> Q <sub>rr</sub>	I <sub>F</sub> = 245 A	T <sub>j</sub> = 125 °C				A µC
E <sub>rr</sub>	V <sub>GE</sub> = -8 V; V <sub>CC</sub> = 300 V					mJ
R <sub>th(j-c)D</sub>	per diode			0,26		K/W
	eling diode (Neutral (	Clamp Diode)				
$V_F = V_{EC}$	$I_{Fnom}$ = 245 A; $V_{GE}$ = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev</sub> .		1,35	1,6	V
		$T_j = 125 ^{\circ}C_{chiplev.}$ $T_j = 25 ^{\circ}C$		1,35	1,6	V
$V_{F0}$		T <sub>j</sub> = 25 °C		1	1,1	V
		T <sub>j</sub> = 125 °C		0,9	1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,42	2	V
		T <sub>j</sub> = 125 °C T <sub>j</sub> = 125 °C		1,8	2,4	V
I <sub>RRM</sub> Q <sub>rr</sub>	I <sub>F</sub> = 245 A	T <sub>j</sub> = 125 °C				A µC
E <sub>rr</sub>	V <sub>GE</sub> = 0 V; V <sub>CC</sub> = 600 V			5		mJ
R <sub>th(j-c)FD</sub>	per diode			0,26		K/W
$M_s$	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					310	g
	ture sensor					_
R <sub>100</sub>	$T_s$ =100°C ( $R_{25}$ =5kΩ)			493±5%		Ω
						K

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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